

SPREAD SPECTRUM CLOCK GENERATOR

MK1726-08

Description

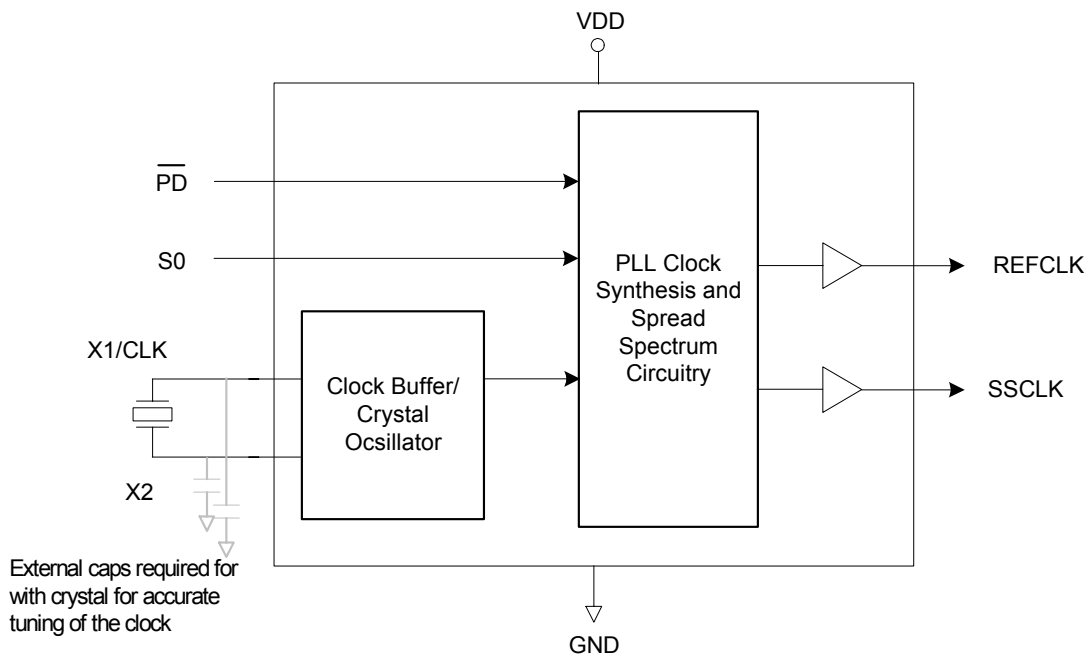
The MK1726-08 generates a low EMI output clock and a reference clock from a clock or crystal input. The part is designed to lower EMI through the application of spreading a clock. Using IDT's proprietary mix of analog and digital Phase-Locked Loop (PLL) technology, the device spreads the frequency spectrum of the output, reducing the frequency amplitude peaks by several dB depending on spread range. The MK1726-08 offers a range of down spread from a high speed clock or crystal input. The MK1726-08 generates one modulated (SSCLK) and unmodulated (REFCLK) clock and is compatible with Cypress CY25819. The modulated clock is controlled by the select pin, and the unmodulated clock has the same frequency as the input clock or crystal.

Features

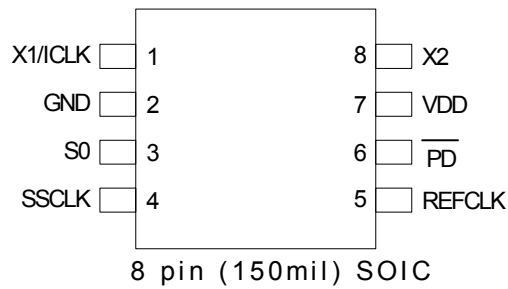
- Packaged in 8-pin SOIC
- Available in Pb (lead) free package
- Input frequency range 16- 32 MHz
- Provides modulated and unmodulated clocks
- Accepts a clock or crystal input
- Provides down spread modulation
- Provides power down function
- Reduce electromagnetic interference (EMI) by 8-16 db
- Operating voltage of 3.3 V
- Advanced, low-power CMOS process

NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

Block Diagram



Pin Assignment



Spread Percentage Select Table

| S0 | Spread Direction | Spread Percentage (%) |
|----|------------------|-----------------------|
| 0 | Down | -1.8 |
| 1 | Down | -2.5 |
| M | Down | -0.6 |

0 = connect to GND

M= unconnected

1 = connect directly to VDD

* Default has internal pull up resistor to VDD

Pin Descriptions

| Pin Number | Pin Name | Pin Type | Pin Description |
|------------|------------------------|----------|--|
| 1 | X1/CLK | Input | Connect to 16-32 MHz crystal or clock. |
| 2 | GND | Power | Connect to ground. |
| 3 | S0 | Input | Select spread percentage per table above. Internal pull-up. |
| 4 | SSCLK | Output | Spread spectrum clock output per table above. |
| 5 | REFCLK | Power | CMOS level clock output matches the nominal frequency of the input crystal or clock. |
| 6 | $\overline{\text{PD}}$ | Input | Power down tri-state. This pin powers down entire chip and tri-state the outputs when low. Internal pull-up. |
| 7 | VDD | Power | Connect to 3.3 V. |
| 8 | X2 | Input | Connect to 16-32 MHz crystal or leave unconnected. |

External Components

The MK1726-08 requires a minimum number of external components for proper operation.

Decoupling Capacitor

A decoupling capacitor of 0.01 μ F must be connected between VDD and GND, as close to these pins as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

Series Termination Resistor

When the PCB trace between the clock output and the load is over 1 inch, series termination should be used. To series terminate a 50 Ω trace (a commonly used trace impedance) place a 33 Ω resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is 20 Ω .

PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

- 1) The 0.01 μ F decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via.
- 2) To minimize EMI, the 33 Ω series termination resistor (if needed) should be placed close to the clock output.
- 3) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the MK1726-08. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

Crystal Information

The crystal used should be a fundamental mode (do not use third overtone), parallel resonant. Crystal capacitors should be connected from pins X1 to ground and X2 to ground to optimize the initial accuracy. The value of these capacitors

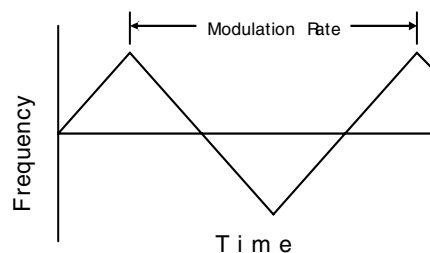
is given by the following equation:

$$\text{Crystal caps (pF)} = (C_L - 6) \times 2$$

In the equation, C_L is the crystal load capacitance. So, for a crystal with a 16 pF load capacitance, two 20 pF [(16-6) x 2] capacitors should be used.

Spread Spectrum Profile

The MK1726-08 low EMI clock generator uses an optimized frequency slew rate algorithm to facilitate down stream tracking of zero delay buffers and other PLL devices. The frequency modulation amplitude is constant with variations of the input frequency.



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK1726-08. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item | Rating |
|-------------------------------|---------------------|
| Supply Voltage, VDD | 7 V |
| All Inputs and Outputs | -0.5 V to VDD+0.5 V |
| Ambient Operating Temperature | 0 to +70° C |
| Storage Temperature | -65 to +150° C |
| Junction Temperature | 125° C |
| Soldering Temperature | 260° C |

Recommended Operation Conditions

| Parameter | Min. | Typ. | Max. | Units |
|---|-------|------|------|-------|
| Ambient Operating Temperature | 0 | | +70 | °C |
| Power Supply Voltage (measured in respect to GND) | +2.97 | | 3.63 | V |

DC Electrical Characteristics

Unless stated otherwise, VDD = 3.3 V \pm 10%, Ambient Temperature 0 to +70° C

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|----------------------|------------------|---|----------------------|----------------------|----------------------|-------|
| Power Supply Range | V _{DD} | | 2.97 | 3.3 | 3.63 | V |
| Input High Voltage | V _{INH} | S0 Input | 0.85 V _{DD} | V _{DD} | V _{DD} | V |
| Input Middle Voltage | V _{INM} | S0 Input | 0.40 V _{DD} | 0.50 V _{DD} | 0.60 V _{DD} | V |
| Input Low Voltage | V _{INL} | S0 Input | 0.0 | 0.0 | 0.15 V _{DD} | V |
| Output High Voltage | V _{OH1} | I _{OH} =4 ma, SSCLK and REFCLK | 2.4 | | | V |
| Output High Voltage | V _{OH2} | I _{OH} =6 ma, SSCLK and REFCLK | 2.0 | | | V |
| Output Low Voltage | V _{OL1} | I _{OL} =4 ma, SSCLK | | | 0.4 | V |
| Output Low Voltage | V _{OL2} | I _{OL} =10 ma, SSCLK | | | 1.2 | V |
| Power Supply Current | I _{DD2} | F _{IN} =32 MHz, no load | | 19.0 | 23.0 | mA |
| Power Supply Current | I _{DD3} | $\overline{\text{PD}}$ = GND | | 150 | 250 | uA |

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|---------------------------|----------|------------|------|------|------|------------|
| Input Capacitance | C_{IN} | | | 5 | | pF |
| clock output impedance | | | | 20 | | ohms |
| Internal pull-up resistor | R_{PU} | SEL | | 360 | | k Ω |

AC Electrical Characteristics

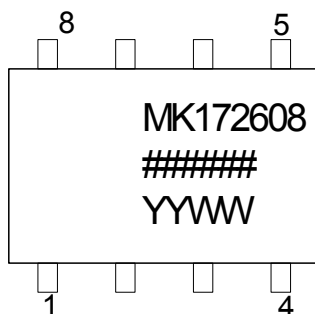
Unless stated otherwise, $V_{DD} = 3.3\text{ V} \pm 10\%$, Ambient Temperature 0 to $+70^{\circ}\text{C}$

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|------------------------------|--------|--|------|---------|------|-------|
| Input Clock Frequency | | | 16 | | 32 | MHz |
| Output Clock Frequency | | | 16 | | 32 | MHz |
| Clock Rise Time | trise1 | SSCLK and REFCLK, 0.4 V to 2.4 V | 2.0 | 3.0 | 4.0 | ns |
| Clock Fall Time | tfall1 | SSCLK and REFCLK, 0.4 V to 2.4 V | 2.0 | 3.0 | 4.0 | ns |
| Input Clock Duty Cycle | | X_1 | 20 | 50 | 80 | % |
| Output Clock Duty Cycle | | SSCLK and REFCLK @ 1.5V | 45 | 50 | 55 | % |
| Cycle-to-Cycle Jitter | | SSCLK, $F_{in}=21\text{MHz}$, $F_{out}=21\text{MHz}$ | | 250 | 350 | ps |
| Cycle-to-Cycle Jitter | | REFCLK, $F_{in}=21\text{MHz}$, $F_{out}=21\text{MHz}$ | | 275 | 375 | ps |
| EMI Peak Frequency Reduction | | | | 8 to 16 | | dB |

Thermal Characteristics

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|--|---------------|----------------|------|------|------|----------------------|
| Thermal Resistance Junction to Ambient | θ_{JA} | Still air | | 110 | | $^{\circ}\text{C/W}$ |
| | θ_{JA} | 1 m/s air flow | | 100 | | $^{\circ}\text{C/W}$ |
| | θ_{JA} | 3 m/s air flow | | 80 | | $^{\circ}\text{C/W}$ |
| Thermal Resistance Junction to Case | θ_{JC} | | | 35 | | $^{\circ}\text{C/W}$ |

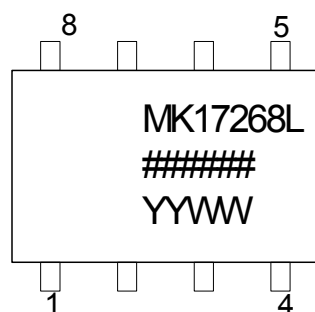
Marking Diagram



Notes:

1. ##### is the lot code.
2. YYWW is the last two digits of the year, and the week number that the part was assembled.

Marking Diagram (Pb free)

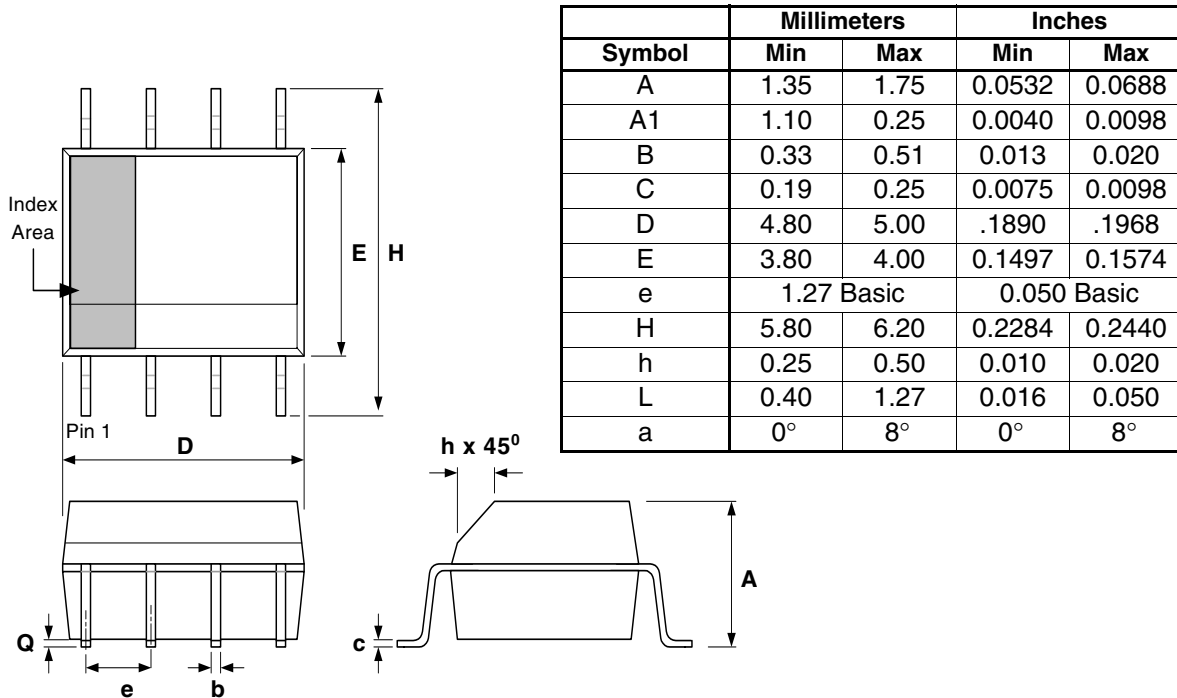


Notes:

1. ##### is the lot code.
2. YYWW is the last two digits of the year, and the week number that the part was assembled.
3. "L" designates Pb (lead) free package.

Package Outline and Package Dimensions (8 pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

| Part / Order Number | Marking | Shipping Packaging | Package | Temperature |
|---------------------|-------------------|--------------------|------------|-------------|
| MK1726-08S* | see previous page | Tubes | 8-pin SOIC | 0 to +70° C |
| MK1726-08STR* | see previous page | Tape and Reel | 8-pin SOIC | 0 to +70° C |
| MK1726-08SLF | see previous page | Tubes | 8-pin SOIC | 0 to +70° C |
| MK1726-08SLFTR | see previous page | Tape and Reel | 8-pin SOIC | 0 to +70° C |

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“LF” designates Pb (lead) free package.

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